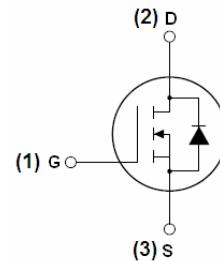


## • Product Summary

Part #	V <sub>DS</sub>	R <sub>DS(on).typ</sub> (@V <sub>GS</sub> =4.5V)	R <sub>DS(on).typ</sub> (@V <sub>GS</sub> =2.5V)	I <sub>D</sub>
EFM160N02D	20V	16mΩ	22mΩ	20A

## • Description

- The EFM160N02D is the high cell density trenched
- N-ch MOSFETs which provide excellent
- RDSON and gate charge for most of the
- synchronous buck converter applications.
- The EFM160N02D meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.



N-Channel MOSFET



TO-252-2L

## • Ordering Information:

Part NO.	EFM160N02D
Marking	160N02D *****
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

## • Absolute Maximum Ratings (T<sub>C</sub>=25°C)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Drain Current-Continuous	I <sub>D</sub>	20	A
Drain Current-Pulsed <sup>(Note 1)</sup>	I <sub>DM</sub>	40	A
Maximum Power Dissipation	P <sub>D</sub>	5	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 To 150	°C

## • Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	R <sub>θJA</sub>	62	°C/W
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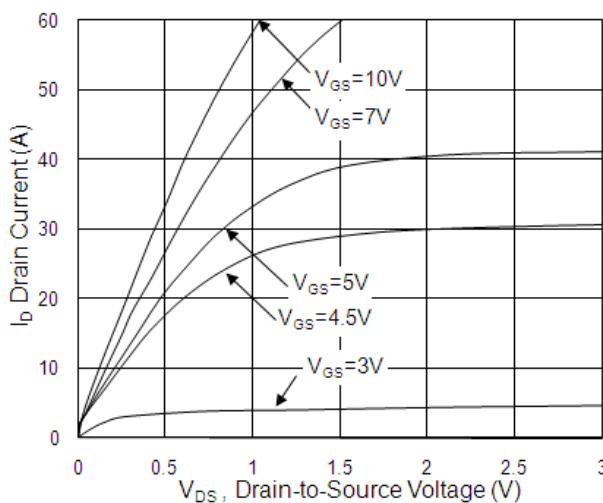
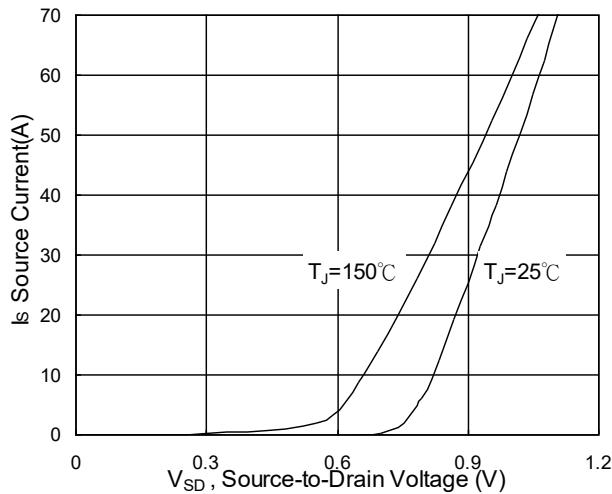
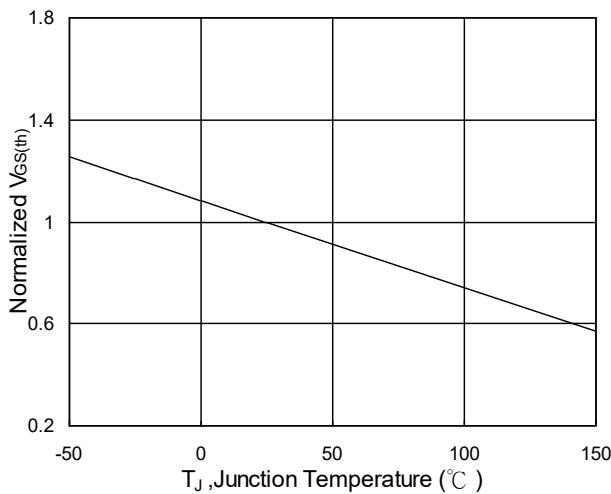
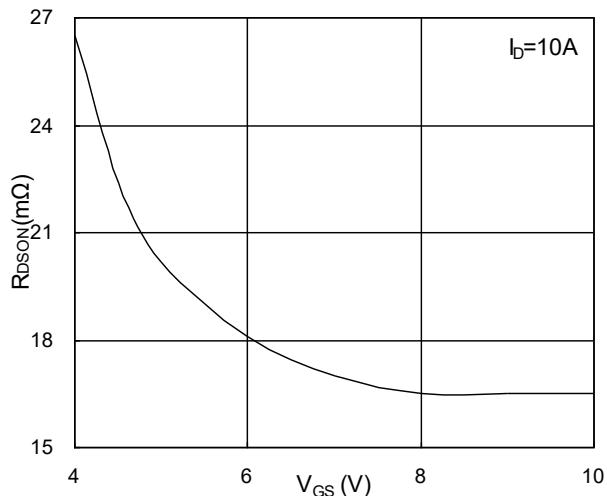
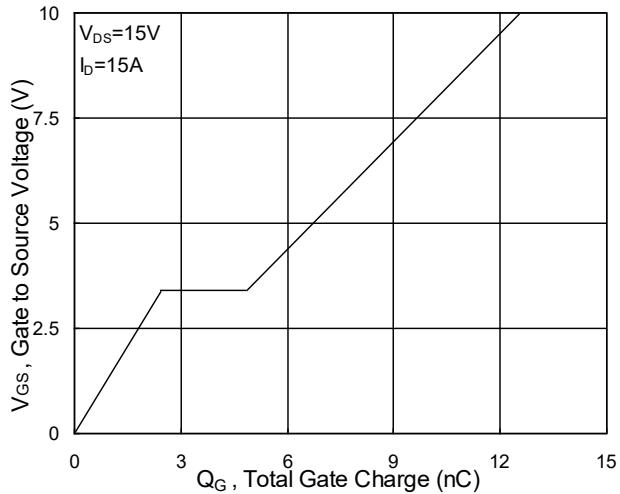
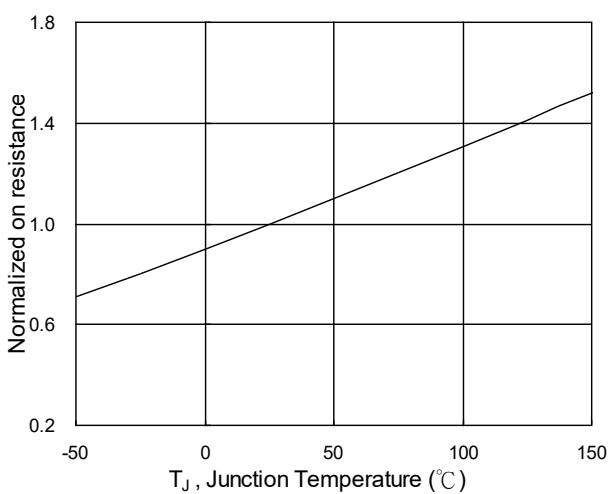
**• Static Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)**

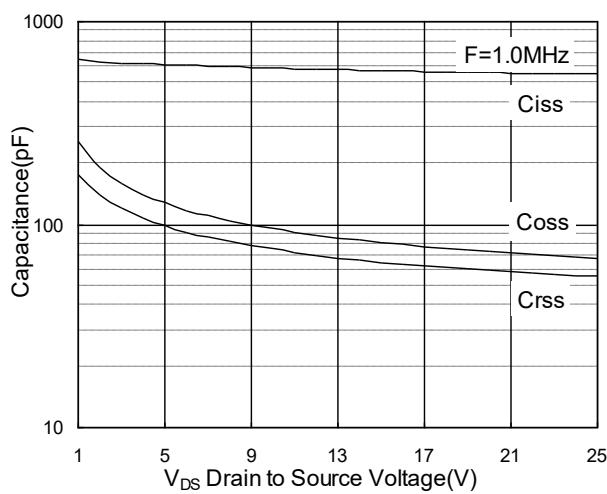
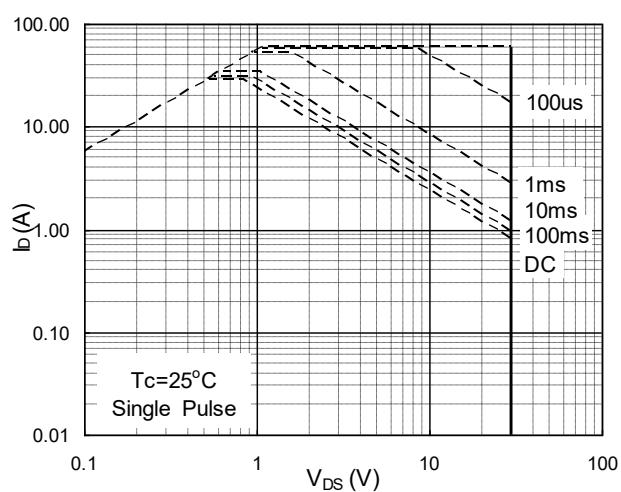
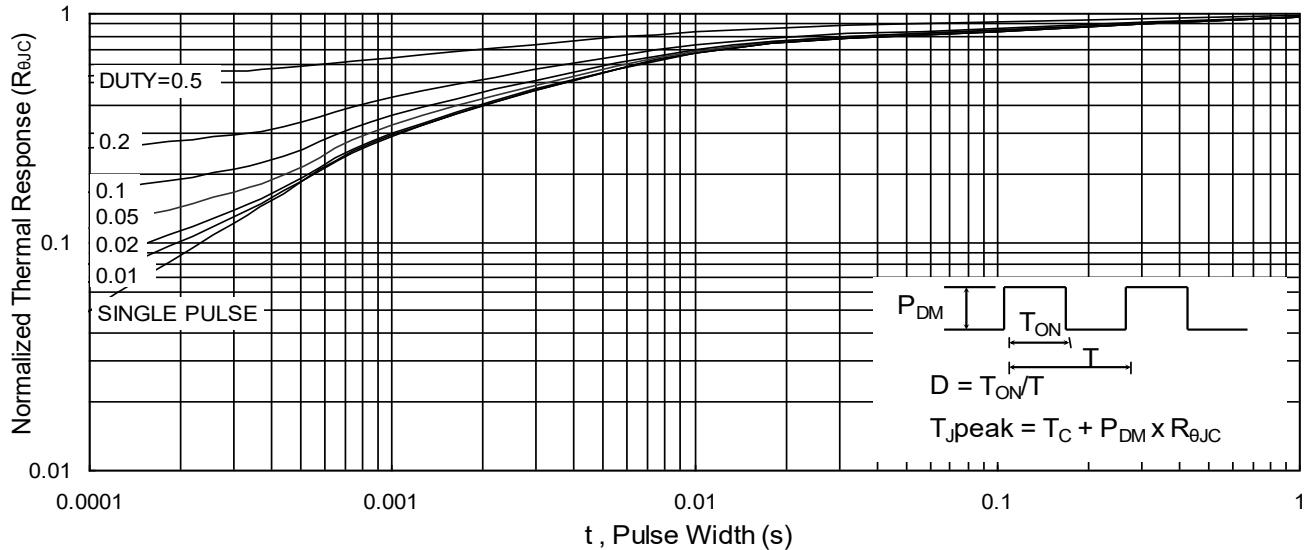
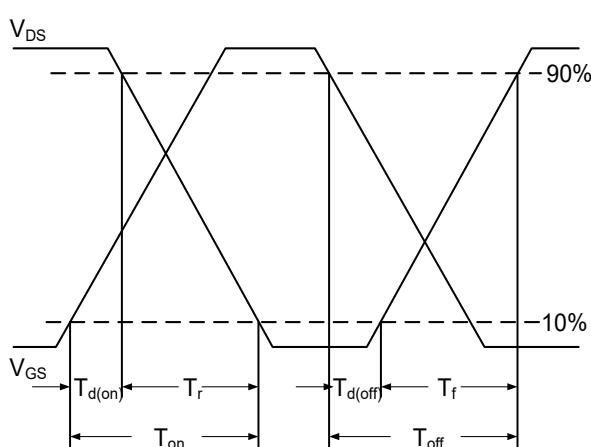
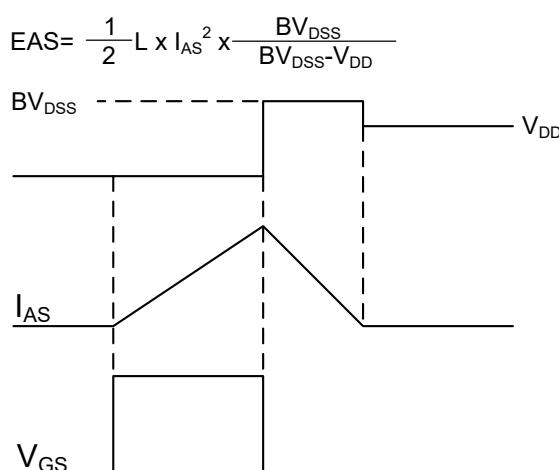
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V} I_{\text{D}}=250\mu\text{A}$	20	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=20\text{V} V_{\text{GS}}=0\text{V}$	--	--	1	nA
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 12\text{V} V_{\text{DS}}=0\text{V}$	--	--	$\pm 100$	nA
<b>On Characteristics</b> <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}} I_{\text{D}}=250\mu\text{A}$	0.4	0.8	1.2	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=4.5\text{V} I_{\text{D}}=10\text{A}$	--	16	24	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V} I_{\text{D}}=6\text{A}$	--	22	30	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V} I_{\text{D}}=15\text{A}$	--	22	--	S
Gate Resistance	$R_g$	$F=1.0\text{MHz}$	--	2.5	--	$\Omega$
<b>Dynamic Characteristics</b> <small>(Note 4)</small>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V} V_{\text{GS}}=0\text{V}$ $F=1.0\text{MHz}$	--	472	--	PF
Output Capacitance	$C_{\text{oss}}$		--	71	--	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	55	--	PF
<b>Switching Characteristics</b> <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=15\text{V} I_{\text{D}}=15\text{A}$ $V_{\text{GS}}=4.5\text{V} R_{\text{G}}=3.3\Omega$	--	4	--	nS
Turn-on Rise Time	$t_r$		--	7.6	--	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		--	21	--	nS
Turn-Off Fall Time	$t_f$		--	4	--	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=15\text{V} I_{\text{D}}=15\text{A}$ $V_{\text{GS}}=4.5\text{V}$	--	6.2	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	2.4	--	nC
Gate-Drain Charge	$Q_{\text{gd}}$		--	2.5	--	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <small>(Note 3)</small>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V} I_{\text{S}}=1\text{A}$	--	--	1.2	V
Diode Forward Current <small>(Note 2)</small>	$I_{\text{S}}$		--	--	20	A

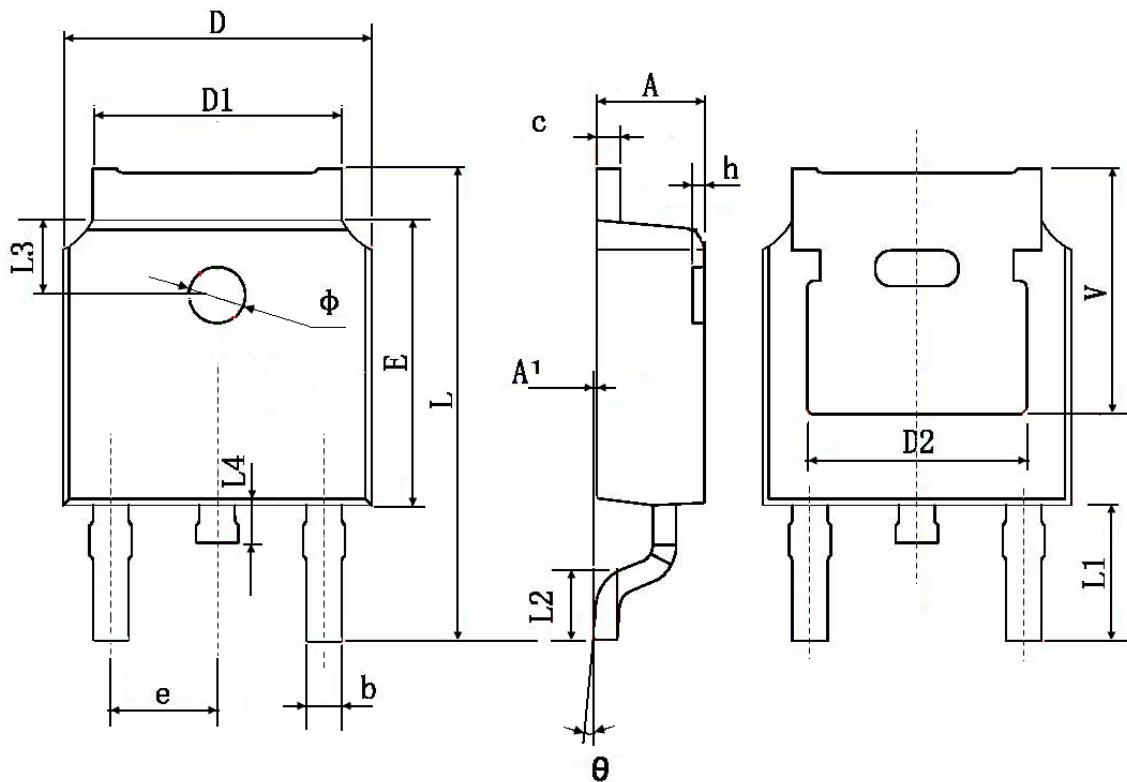
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=21\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

## • Typical Characteristics


**Fig.1 Typical Output Characteristics**

**Fig.3 Forward Characteristics Of Reverse**

**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$** 

**Fig.2 On-Resistance v.s Gate-Source**

**Fig.4 Gate-Charge Characteristics**

**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

**TO-252 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.83 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	